

MATERIAL SPECIFICATION

Material

Silver Copper, C10700
Condition – Cold Rolled Plate

Chemical composition

Ag: 0.08 to 0.12 %
P: 0.001 to 0.007 %
Copper: Balance Material
Standard: DIN 17666

Physical properties:

Electrical conductivity : min 55 m/ohm/sq.mm at min. 95 IACS
Thermal conductivity : min 370 W/M/k
Co. eff. of thermal expansion : min 17.7 (20-300 deg. C) 10 exp -6/K
Recrystallisation temp. : min 370 deg. C

Mechanical Properties:

0.2% of proof stress : min 245 N/sq.mm
Tensile strength : min 280 N/sq.mm
Elongation (A5%) : min 12
Hardness (HB2.5/62.5) : min 95
Modulus of elasticity : min 120 N/Sq.mm 10 exp.3

Sizes & Quantities

1. 80(-2/+0) x 355(-2/+0) x 1010(-2/+0) mm – 84 Nos. (21588 Kgs)
2. 90(-2/+0) x 330(-0/+2) x 1010(-2/+0) mm – 60 Nos. (16200 Kgs)
3. 90(-2/+0) x 260(-2/+0) x 1010(-2/+0) mm – 24 Nos. (5088 Kgs)